

## 2. Features

- Expandable 5 channel, bidirectional buffer
- I<sup>2</sup>C-bus and SMBus compatible
- Active HIGH individual repeater enable inputs
- Open-drain input/outputs
- Lock-up free operation
- Supports arbitration and clock stretching across the repeater
- Accommodates Standard-mode and Fast-mode I<sup>2</sup>C-bus devices and multiple masters
- Powered-off high-impedance I<sup>2</sup>C-bus pins
- Operating supply voltage range of 2.3 V to 3.6 V
- 5 V tolerant I<sup>2</sup>C-bus and enable pins
- 0 Hz to 400 kHz clock frequency<sup>2</sup>
- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Package offerings: SO20 and TSSOP20

## 3. Ordering information

**Table 1. Ordering information**

$T_{amb} = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$

Type number	Topside mark	Package		
		Name	Description	Version
PCA9518AD	PCA9518AD	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
PCA9518APW	PA9518A	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1

2. The maximum system operating frequency may be less than 400 kHz because of the delays added by the repeater.

4. Block diagram

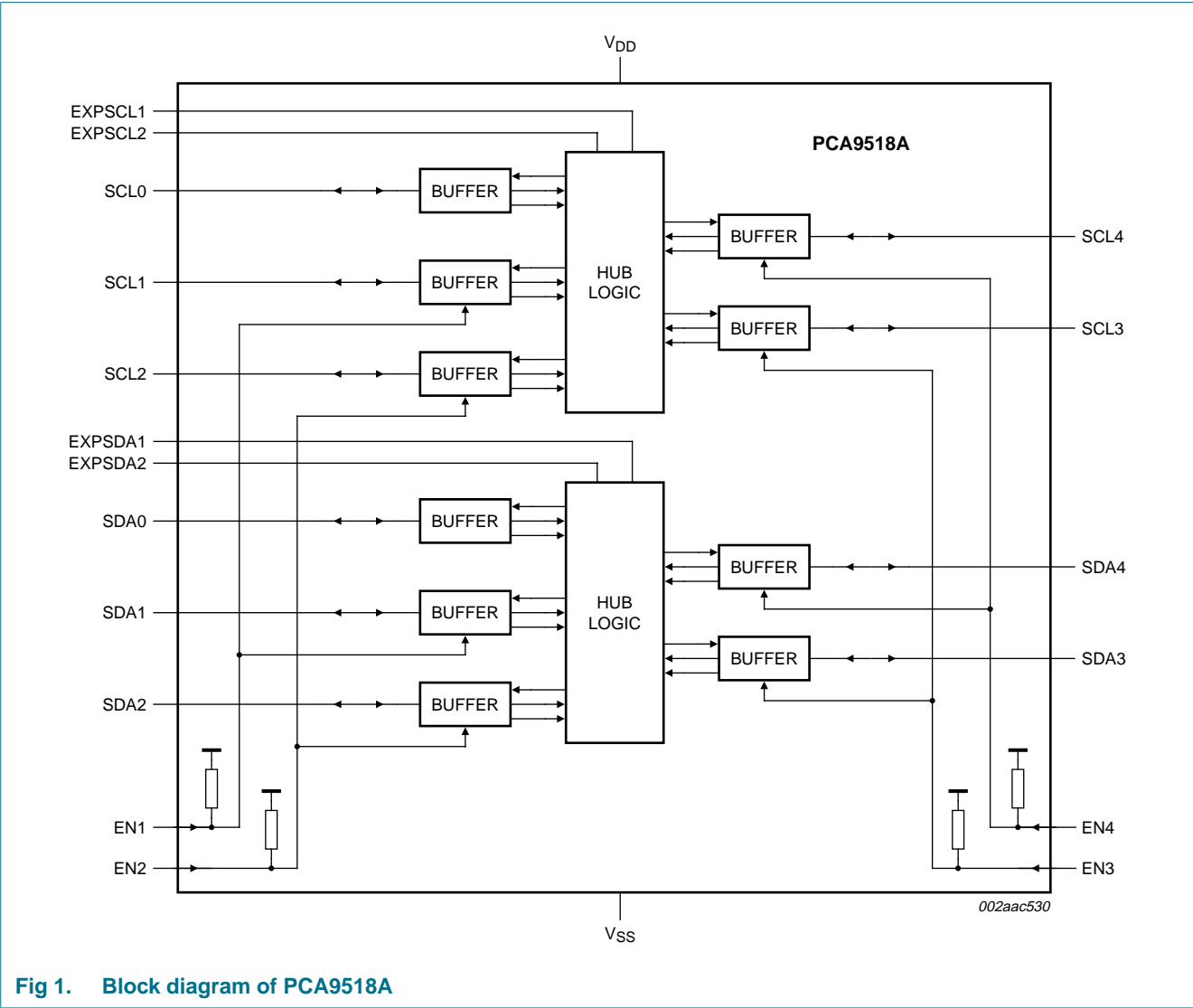


Fig 1. Block diagram of PCA9518A

A more detailed view of [Figure 1](#) buffer is shown in [Figure 2](#).

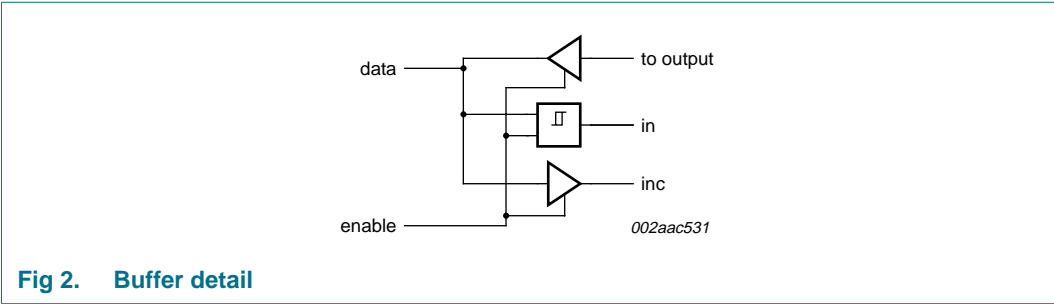
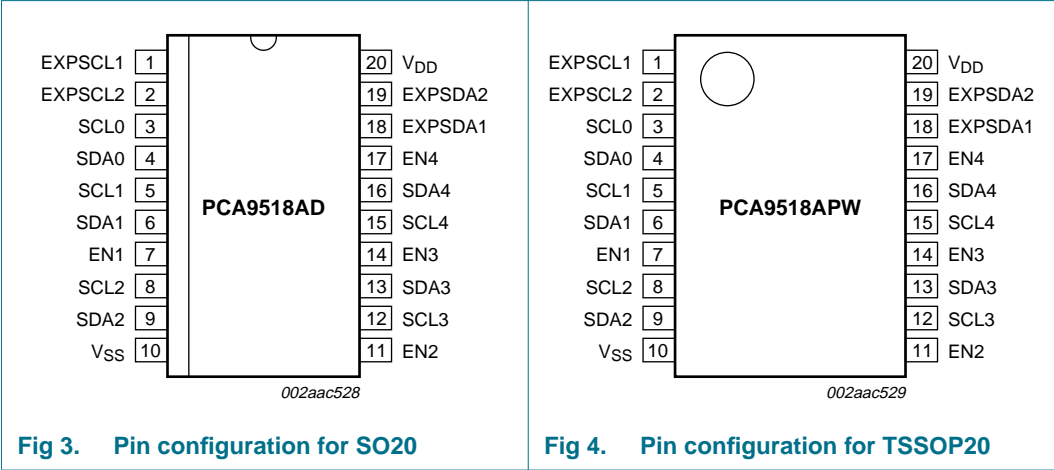


Fig 2. Buffer detail

The output pull-down voltage of each internal buffer is set for approximately 0.5 V, while the input threshold of each internal buffer is set about 0.07 V lower, when the output is internally driven LOW. This prevents a lock-up condition from occurring.

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
EXPSCL1	1	expandable serial clock pin 1
EXPSCL2	2	expandable serial clock pin 2
SCL0	3	serial clock bus 0
SDA0	4	serial data bus 0
SCL1	5	serial clock bus 1
SDA1	6	serial data bus 1
EN1	7	active HIGH bus 1 enable input
SCL2	8	serial clock bus 2
SDA2	9	serial data bus 2
Vss	10	supply ground
EN2	11	active HIGH bus 2 enable input
SCL3	12	serial clock bus 3
SDA3	13	serial data bus 3
EN3	14	active HIGH bus 3 enable input
SCL4	15	serial clock bus 4
SDA4	16	serial data bus 4
EN4	17	active HIGH bus 4 enable input
EXPSDA1	18	expandable serial data pin 1
EXPSDA2	19	expandable serial data pin 2
VDD	20	supply voltage

## 6. Functional description

The PCA9518A CMOS integrated circuit is a five-way hub repeater, which enables I<sup>2</sup>C-bus and similar bus systems to be expanded in increments of five with only one repeater delay and no functional degradation of system performance.

The PCA9518A CMOS integrated circuit contains five multi-directional, open-drain buffers specifically designed to support the standard low-level contention arbitration of the I<sup>2</sup>C-bus. Except during arbitration or clock stretching, the PCA9518A acts like a pair of non-inverting, open-drain buffers, one for SDA and one for SCL.

Refer to [Figure 1 “Block diagram of PCA9518A”](#).

### 6.1 Enable

The enable pins EN1 through EN4 are active HIGH and have internal pull-up resistors. Each enable pin ENn controls its associated SDAn and SCLn ports. When LOW, the ENn pin blocks the inputs from SDAn and SCLn, as well as disabling the output drivers on the SDAn and SCLn pins. The enable pins should only change state when both the global bus and the local port are in an idle state to prevent system failures.

The active HIGH enable pins allow the use of open-drain drivers which can be wire-ORed to create a distributed enable where either centralized control signal (master) or spoke signal (sub-master) can enable the channel when it is idle.

Unused channels must have pull-up resistors unless their enable pin (ENn) is **always** LOW. Port 0 must always have pull-up resistors since it is always present in the bus and cannot be disabled.

### 6.2 Expansion

The PCA9518A includes 4 open-drain I/O pins used for expansion. Two expansion pins, EXPSDA1 and EXPSDA2 are used to communicate the internal state of the serial data within each hub to the other hubs. The EXPSDA1 pins of all hubs are connected together to form an open-drain bus. Similarly, all EXPSDA2 pins, EXPSCL1 pins, and all EXPSCL2 pins are connected together forming a 4-wire bus between hubs.

When it is necessary to be able to deselect every port, each expansion device only contributes 4 ports which can be enabled or disabled because the fifth does not have an enable pin.

Pull-up resistors are required on the EXPxxxn<sup>3</sup> pins even if only one PCA9518A is used.

### 6.3 I<sup>2</sup>C-bus systems

As with the standard I<sup>2</sup>C-bus system, pull-up resistors are required to provide the logic HIGH levels on the buffered bus. (Standard open-collector or open-drain configuration of the I<sup>2</sup>C-bus). The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. This part is designed to work with Standard-mode (0 Hz to 100 kHz) and Fast-mode (0 Hz to 400 kHz) I<sup>2</sup>C-bus devices in addition to SMBus devices. Standard-mode I<sup>2</sup>C-bus devices only specify 3 mA output drive; this limits the termination current to 3 mA in a generic I<sup>2</sup>C-bus system where

3. 'xxxn' is SDA1, SDA2, SCL1 or SCL2. 'xxx' is SDA or SCL.

Standard-mode devices and multiple masters are possible. Please see application note *AN255, I<sup>2</sup>C/SMBus Repeaters, Hubs and Expanders* for additional information on sizing resistors.

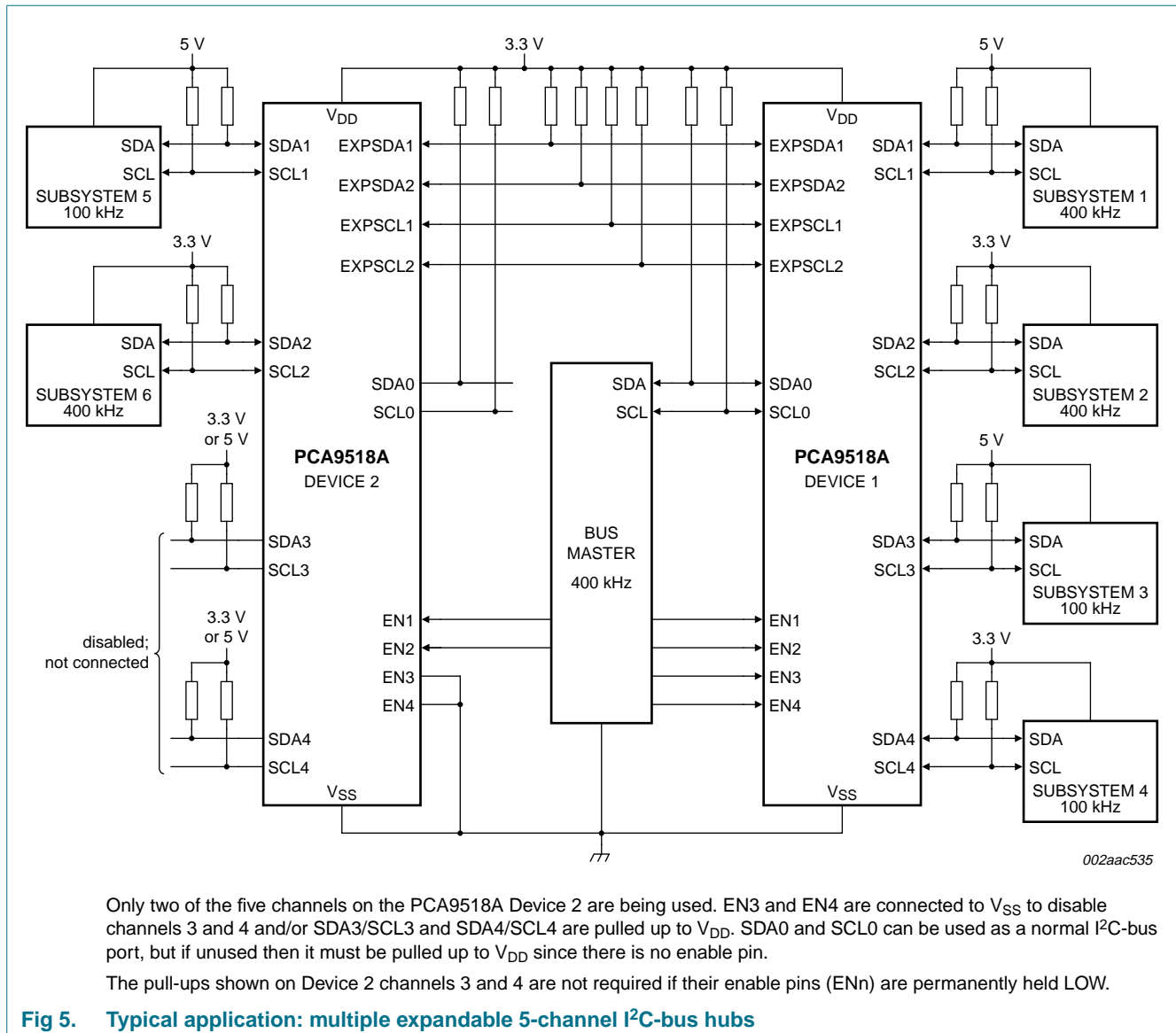
## 7. Application design-in information

A typical application is shown in [Figure 5](#). In this example, the system master is running on a 3.3 V I<sup>2</sup>C-bus while the slaves are connected to a 3.3 V or 5 V bus. All buses run at 100 kHz unless slave 3, slave 4 and slave 5 are isolated from the bus. Then the master bus and slave 1, slave 2 and slave 6 can run at 400 kHz.

Any segment of the hub can talk to any other segment of the hub. Bus masters and slaves can be located on any segment with 400 pF load allowed on each segment.

The PCA9518A is 5 V tolerant, so it does not require any additional circuitry to translate between the different bus voltages.

When one port of the PCA9518A is pulled LOW by a device on the I<sup>2</sup>C-bus, a CMOS hysteresis type input detects the falling edge and drives the EXPxxx1 line LOW, when the EXPxxx1 voltage is less than 0.5V<sub>DD</sub>, the other ports are pulled down to the V<sub>OL</sub> of the PCA9518A which is typically 0.5 V.

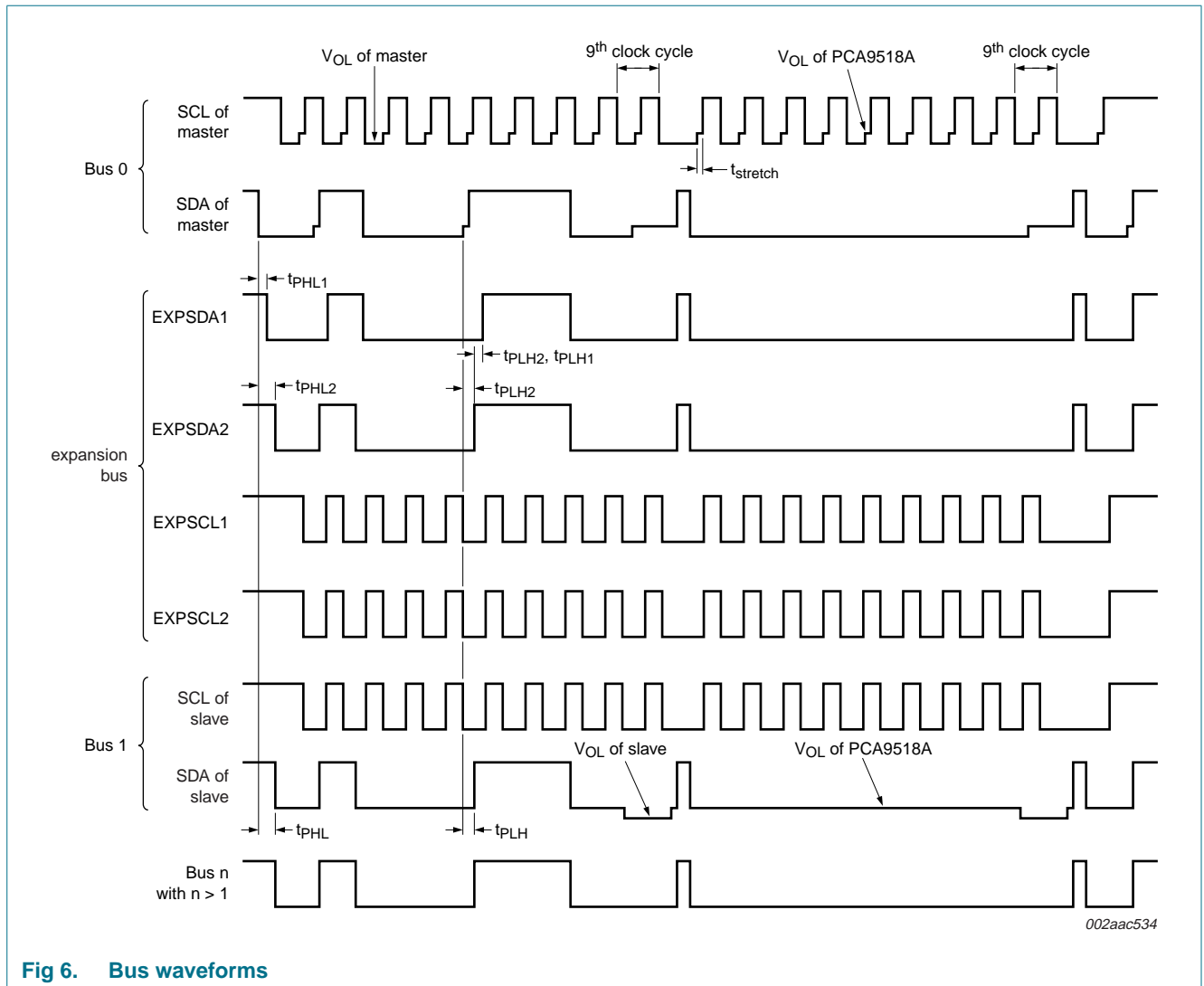


**Fig 5. Typical application: multiple expandable 5-channel I<sup>2</sup>C-bus hubs**

In order to illustrate what would be seen in a typical application, refer to [Figure 6](#). If the bus master in [Figure 5](#) were to write to the slave through the PCA9518A, we would see the waveform shown in [Figure 6](#). This looks like a normal I<sup>2</sup>C-bus transmission except for the small foot preceding each clock LOW-to-HIGH transition and proceeding each data LOW-to-HIGH transition for the master. The foot height is the difference between the LOW level driven by the master and the higher voltage LOW level driven by the PCA9518A repeater. Its width corresponds to an effective clock stretching coming from the PCA9518A that delays the rising edge of the clock. That same magnitude of delay is seen on the rising edge of the data. The foot on the rising edge of the data is extended through the 9<sup>th</sup> clock pulse as the PCA9518A repeats the acknowledge from the slave to the master. The clock of the slave looks normal except the V<sub>OL</sub> is the ~0.5 V level generated by the PCA9518A. The SDA at the slave has a particularly interesting shape during the 9<sup>th</sup> clock cycle where the slave pulls the line below the value driven by the PCA9518A during

the acknowledge and then returns to the PCA9518A level creating a foot before it completes the LOW-to-HIGH transition. SDA lines other than the one with the master and the one with the slave have a uniform LOW level driven by the PCA9518A repeater.

The other four waveforms are the expansion bus signals and are included primarily for timing reference points. All timing on the expansion bus is with respect to  $0.5V_{DD}$ . EXPSDA1 is the expansion bus that is driven LOW whenever any SDA pin falls below  $0.3V_{DD}$ . EXPSDA2 is the expansion bus that is driven LOW whenever any pin is  $\leq 0.4$  V. EXPSCL1 is the expansion bus that is driven LOW whenever any SCL pin falls below  $0.3V_{DD}$ . EXPSCL2 is the expansion bus that is driven LOW whenever any SCL pin is  $\leq 0.4$  V. The EXPSDA2 returns HIGH after the SDA pin that was the last one being held below 0.4 V by an external driver starts to rise. The last SDA to rise above 0.4 V is held down by the PCA9518A to  $\sim 0.5$  V until after the delay of the circuit which determines that it was the last to rise, then it is allowed to rise above the  $\sim 0.5$  V level driven by the PCA9518A. Considering the bus 0 SDA to be the last one to go above 0.4 V, then the EXPSDA1 returns to HIGH after the EXPSDA2 is HIGH and either the bus 0 SDA rise time is 1  $\mu$ s or, when the bus 0 SDA reaches  $0.7V_{DD}$ , whichever occurs first. After both EXPSDA2 and EXPSDA1 are HIGH the rest of the SDA lines are allowed to rise. The same description applies for the EXPSCL1, EXPSCL2, and SCL pins.



**Fig 6. Bus waveforms**

It is important to note that any arbitration or clock stretching events on Bus 1 require that the  $V_{OL}$  of the devices on Bus 1 be 70 mV below the  $V_{OL}$  of the PCA9518A (see  $V_{OL}-V_{ILc}$  in the [Section 9 "Static characteristics"](#)) to be recognized by the PCA9518A and then transmitted to Bus 0.



## 8. Limiting values

**Table 3. Limiting values***In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DD</sub>	supply voltage	V <sub>DD</sub> to V <sub>SS</sub>	[1] -0.5	+6	V
V <sub>I2C-bus</sub>	I <sup>2</sup> C-bus voltage	SCL or SDA	[1] -0.5	+6	V
I <sub>I</sub>	input current	any pin	-	50	mA
P <sub>tot</sub>	total power dissipation		-	300	mW
T <sub>stg</sub>	storage temperature		-55	+125	°C
T <sub>amb</sub>	ambient temperature	operating	-40	+85	°C

[1] Voltages with respect to pin V<sub>SS</sub>.

## 9. Static characteristics

**Table 4. Static characteristics**

$V_{DD} = 3.0\text{ V to }3.6\text{ V}$ <sup>[1]</sup>;  $V_{SS} = 0\text{ V}$ ;  $T_{amb} = -40\text{ °C to }+85\text{ °C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Supplies</b>						
$V_{DD}$	supply voltage		3.0	3.3	3.6	V
$I_{CCH}$	HIGH-level supply current	both channels HIGH $V_{DD} = 3.6\text{ V}$ ; $SDAn = SCLn = V_{DD}$	-	7.5	10	mA
$I_{CCL}$	LOW-level supply current	both channels LOW $V_{DD} = 3.6\text{ V}$ ; one SDA and one SCL = $V_{SS}$ ; other SDA and SCL open	-	9	11	mA
$I_{CCLc}$	contention LOW-level supply current	$V_{DD} = 3.6\text{ V}$ ; $SDAn = SCLn = V_{SS}$	-	9	11	mA
<b>Input SCL; input/output SDA</b>						
$V_{IH}$	HIGH-level input voltage	SCL, SDA	$0.7V_{DD}$	-	5.5	V
$V_{IL}$	LOW-level input voltage	SCL, SDA	<sup>[2]</sup> -0.5	-	$+0.25V_{DD}$	V
$V_{ILc}$	contention LOW-level input voltage	SCL, SDA	<sup>[3]</sup> -0.5	-	+0.4	V
$V_{IK}$	input clamping voltage	$I_I = -18\text{ mA}$	-	-	-1.2	V
$I_{LI}$	input leakage current	$V_I = 3.6\text{ V}$	-	-	$\pm 1$	$\mu\text{A}$
$I_{IL}$	LOW-level input current	SCL, SDA; $V_I = 0.2\text{ V}$	-	-	20	$\mu\text{A}$
$V_{OL}$	LOW-level output voltage	$I_{OL} = 20\text{ }\mu\text{A or }6\text{ mA}$	0.45	0.52	0.6	V
$V_{OL} - V_{ILc}$	difference between LOW-level output and LOW-level input voltage contention	guaranteed by design	-	-	70	mV
$C_i$	input capacitance	$V_I = 3\text{ V or }0\text{ V}$	-	6	8	pF
<b>Enable 1 to Enable 4 (EN1 to EN4)</b>						
$V_{IH}$	HIGH-level input voltage		2.0	-	5.5	V
$V_{IL}$	LOW-level input voltage		-0.5	-	+0.8	V
$I_{IL}$	LOW-level input current	$V_I = 0.2\text{ V}$ ; EN1 to EN4	-	10	30	$\mu\text{A}$
$I_{LI}$	input leakage current		-1	-	+1	$\mu\text{A}$
$C_i$	input capacitance	$V_I = 3.0\text{ V or }0\text{ V}$	-	3	7	pF
<b>Expansion pins (EXPSC1, EXPSC2, EXPSDA1, EXPSDA2)</b>						
$V_{IH}$	HIGH-level input voltage	EXPxxxn	$0.6V_{DD}$	-	5.5	V
$V_{IL}$	LOW-level input voltage	EXPxxxn	-0.5	-	$+0.4V_{DD}$	V
$I_{IL}$	LOW-level input current	$V_I = 0.2\text{ V}$ ; EXPxxxn	-	-	5	$\mu\text{A}$
$V_{OL}$	LOW-level output voltage	$I_{OL} = 12\text{ mA}$	-	-	0.5	V
$C_i$	input capacitance	$V_I = 3.0\text{ V or }0\text{ V}$	-	6	8	pF

[1] For operation between published voltage ranges, refer to worst-case parameter in both ranges.

[2]  $V_{IL}$  specification is for the first LOW level seen by the SDAn/SCLn lines.

[3]  $V_{ILc}$  is for the second and subsequent LOW levels seen by the SDAn/SCLn lines.

**Table 5. Static characteristics**

$V_{DD} = 2.3 \text{ V to } 2.7 \text{ V}$ ;  $V_{SS} = 0 \text{ V}$ ;  $T_{amb} = -40^\circ\text{C to } +85^\circ\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Supplies</b>						
$V_{DD}$	supply voltage		2.3	2.5	2.7	V
$I_{CCH}$	HIGH-level supply current	both channels HIGH $V_{DD} = 2.7 \text{ V}$ ; $SDAn = SCLn = V_{DD}$	-	7.5	10	mA
$I_{CCL}$	LOW-level supply current	both channels LOW $V_{DD} = 2.7 \text{ V}$ ; one SDA and one SCL = $V_{SS}$ ; other SDA and SCL open	-	9	11	mA
$I_{CCLc}$	contention LOW-level supply current	$V_{DD} = 2.7 \text{ V}$ ; $SDAn = SCLn = V_{SS}$	-	9	11	mA
<b>Input SCL; input/output SDA</b>						
$V_{IH}$	HIGH-level input voltage	SCL, SDA	$0.7V_{DD}$	-	5.5	V
$V_{IL}$	LOW-level input voltage	SCL, SDA	[2] -0.5	-	$+0.25V_{DD}$	V
$V_{ILc}$	contention LOW-level input voltage	SCL, SDA	[3] -0.5	-	+0.4	V
$V_{IK}$	input clamping voltage	$I_I = -18 \text{ mA}$	-	-	-1.2	V
$I_{LI}$	input leakage current	$V_I = 2.7 \text{ V}$	-	-	$\pm 1$	$\mu\text{A}$
$I_{IL}$	LOW-level input current	SCL, SDA; $V_I = 0.2 \text{ V}$	-	-	20	$\mu\text{A}$
$V_{OL}$	LOW-level output voltage	$I_{OL} = 20 \mu\text{A}$ or $6 \text{ mA}$	0.45	0.52	0.6	V
$V_{OL} - V_{ILc}$	difference between LOW-level output and LOW-level input voltage contention	guaranteed by design	-	-	70	mV
$C_i$	input capacitance	$V_I = 3 \text{ V}$ or $0 \text{ V}$	-	6	8	pF
<b>Enable 1 to Enable 4 (EN1 to EN4)</b>						
$V_{IH}$	HIGH-level input voltage		2.0	-	5.5	V
$V_{IL}$	LOW-level input voltage		-0.5	-	+0.8	V
$I_{IL}$	LOW-level input current	$V_I = 0.2 \text{ V}$ ; EN1 to EN4	-	10	30	$\mu\text{A}$
$I_{LI}$	input leakage current		-1	-	+1	$\mu\text{A}$
$C_i$	input capacitance	$V_I = 2.3 \text{ V}$ or $0 \text{ V}$	-	3	7	pF
<b>Expansion pins (EXPSC1, EXPSC2, EXPSDA1, EXPSDA2)</b>						
$V_{IH}$	HIGH-level input voltage	EXPxxxn	$0.6V_{DD}$	-	5.5	V
$V_{IL}$	LOW-level input voltage	EXPxxxn	-0.5	-	$+0.4V_{DD}$	V
$I_{IL}$	LOW-level input current	$V_I = 0.2 \text{ V}$ ; EXPxxxn	-	-	5	$\mu\text{A}$
$V_{OL}$	LOW-level output voltage	$I_{OL} = 12 \text{ mA}$	-	-	0.5	V
$C_i$	input capacitance	$V_I = 2.3 \text{ V}$ or $0 \text{ V}$	-	6	8	pF

[1] For operation between published voltage ranges, refer to worst-case parameter in both ranges.

[2]  $V_{IL}$  specification is for the first LOW level seen by the SDAn/SCLn lines.

[3]  $V_{ILc}$  is for the second and subsequent LOW levels seen by the SDAn/SCLn lines.

## 10. Dynamic characteristics

**Table 6. Dynamic characteristics**

$V_{DD} = 3.0\text{ V to }3.6\text{ V}$ ;  $V_{SS} = 0\text{ V}$ ;  $T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	SDA to SDA <sub>n</sub> , or SCL to SCL <sub>n</sub> ; <a href="#">Figure 7</a>	[2][3] 105	202	389	ns
$t_{PLH}$	LOW to HIGH propagation delay	SDA to SDA <sub>n</sub> , or SCL to SCL <sub>n</sub> ; <a href="#">Figure 7</a>	[2][4] 110	259	265	ns
$t_{PHL1}$	HIGH to LOW propagation delay 1	EXPSDA1 to SDA, or EXPSC1 to SCL; <a href="#">Figure 7</a>	109	193	327	ns
$t_{PLH1}$	LOW to HIGH propagation delay 1	EXPSDA1 to SDA, or EXPSC1 to SCL; <a href="#">Figure 7</a>	130	153	179	ns
$t_{PLH2}$	LOW to HIGH propagation delay 2	EXPSDA2 to SDA, or EXPSC2 to SCL; <a href="#">Figure 7</a>	160	234	279	ns
$t_{THL}$	HIGH to LOW output transition time	SDA, SCL; <a href="#">Figure 7</a>	58	110	187	ns
$t_{TLH}$	LOW to HIGH output transition time	SDA, SCL; <a href="#">Figure 7</a>	-	0.85 RC	-	ns
$t_{su}$	set-up time	enable to START condition	300	-	-	ns
$t_h$	hold time	enable after STOP condition	300	-	-	ns

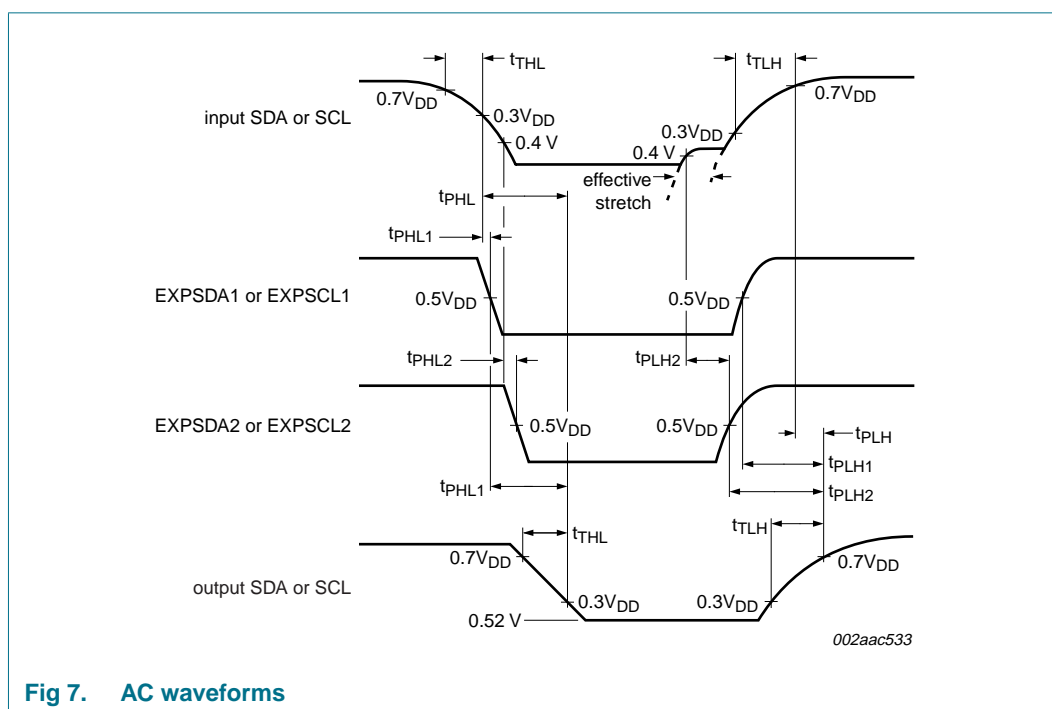
- [1] For operation between published voltage ranges, refer to worst-case parameter in both ranges.
- [2] The SDA and SCL propagation delays are dominated by rise times or fall times. The fall times are mostly internally controlled and are only sensitive to load capacitance. The rise times are RC time constant controlled and therefore a specific numerical value can only be given for fixed RC time constants.
- [3] The SDA HIGH to LOW propagation delay includes the fall time from  $V_{DD}$  to  $0.5V_{DD}$  of the EXPSDA1 or EXPSC1 pins and the SDA or SCL fall time from the quiescent HIGH (usually  $V_{DD}$ ) to below  $0.3V_{DD}$ . The SDA and SCL outputs have edge rate control circuits included which make the fall time almost independent of load capacitance.
- [4] The SDA or SCL LOW to HIGH propagation delay includes the rise time constant from the quiescent LOW to  $0.5V_{DD}$  for the EXPSDA1 or EXPSC2, the rise time constant for the quiescent LOW to  $0.5V_{DD}$  for the EXPSDA1 or EXPSC1, and the rise time constant from the quiescent external driven LOW to  $0.7V_{DD}$  for the SDA or SCL output. All of these rise times are RC time constants determined by the external resistance and total capacitance for the various nodes.

**Table 7. Dynamic characteristics**

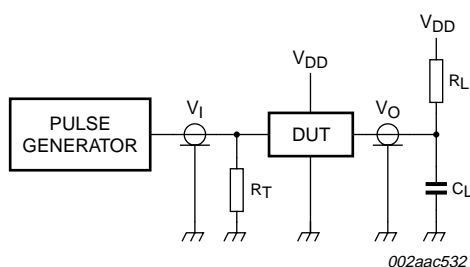
$V_{DD} = 2.3\text{ V to }2.7\text{ V}$ ;  $V_{SS} = 0\text{ V}$ ;  $T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	SDA to SDA <sub>n</sub> , or SCL to SCL <sub>n</sub> ; <a href="#">Figure 7</a>	[2][3] 105	202	389	ns
$t_{PLH}$	LOW to HIGH propagation delay	SDA to SDA <sub>n</sub> , or SCL to SCL <sub>n</sub> ; <a href="#">Figure 7</a>	[2][4] 110	259	265	ns
$t_{PHL1}$	HIGH to LOW propagation delay 1	EXPSDA1 to SDA, or EXPSC1 to SCL; <a href="#">Figure 7</a>	109	193	327	ns
$t_{PLH1}$	LOW to HIGH propagation delay 1	EXPSDA1 to SDA, or EXPSC1 to SCL; <a href="#">Figure 7</a>	130	153	179	ns
$t_{PLH2}$	LOW to HIGH propagation delay 2	EXPSDA2 to SDA, or EXPSC2 to SCL; <a href="#">Figure 7</a>	160	234	279	ns
$t_{THL}$	HIGH to LOW output transition time	SDA, SCL; <a href="#">Figure 7</a>	58	110	187	ns
$t_{TLH}$	LOW to HIGH output transition time	SDA, SCL; <a href="#">Figure 7</a>	-	0.85 RC	-	ns
$t_{su}$	set-up time	enable to START condition	300	-	-	ns
$t_h$	hold time	enable after STOP condition	300	-	-	ns

- [1] For operation between published voltage ranges, refer to worst-case parameter in both ranges.
- [2] The SDA and SCL propagation delays are dominated by rise times or fall times. The fall times are mostly internally controlled and are only sensitive to load capacitance. The rise times are RC time constant controlled and therefore a specific numerical value can only be given for fixed RC time constants.
- [3] The SDA HIGH to LOW propagation delay includes the fall time from  $V_{DD}$  to  $0.5V_{DD}$  of the EXPSDA1 or EXPSC1 pins and the SDA or SCL fall time from the quiescent HIGH (usually  $V_{DD}$ ) to below  $0.3V_{DD}$ . The SDA and SCL outputs have edge rate control circuits included which make the fall time almost independent of load capacitance.
- [4] The SDA or SCL LOW to HIGH propagation delay includes the rise time constant from the quiescent LOW to  $0.5V_{DD}$  for the EXPSDA1 or EXPSC2, the rise time constant for the quiescent LOW to  $0.5V_{DD}$  for the EXPSDA1 or EXPSC1, and the rise time constant from the quiescent external driven LOW to  $0.7V_{DD}$  for the SDA or SCL output. All of these rise times are RC time constants determined by the external resistance and total capacitance for the various nodes.

**Fig 7. AC waveforms**

## 11. Test information



$R_L$  = load resistor; 1.1 k $\Omega$  for I<sup>2</sup>C-bus, and 500  $\Omega$  for EXPxxxn.

$C_L$  = load capacitance includes jig and probe capacitance; 100 pF for I<sup>2</sup>C-bus, and 100 pF for EXPxxxn.

$R_T$  = termination resistance should be equal to  $Z_o$  of the pulse generators.

**Fig 8. Test circuit for open-drain outputs**

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

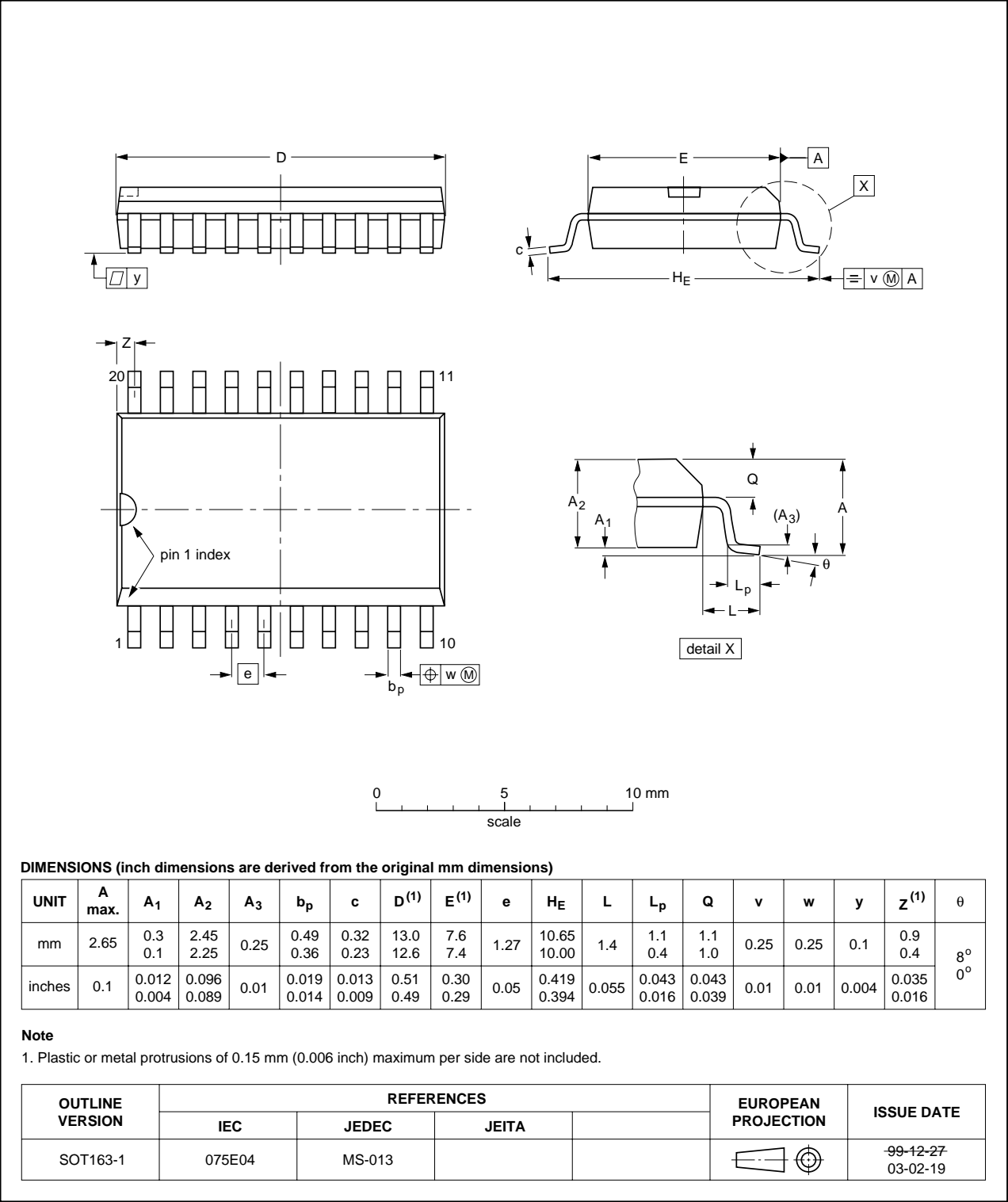


Fig 9. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

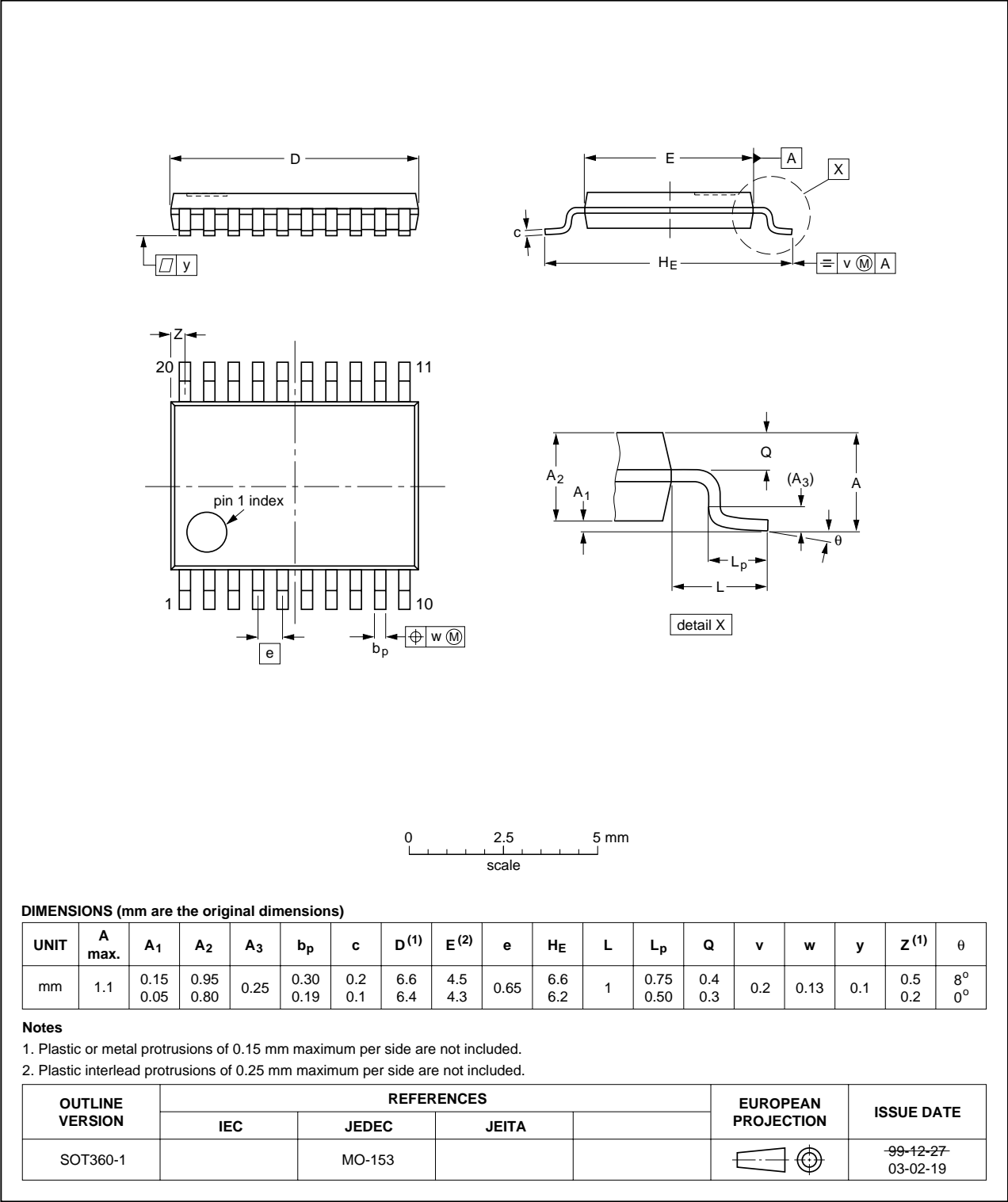


Fig 10. Package outline SOT360-1 (TSSOP20)



## 13. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

### 13.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

### 13.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leadless or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leadless SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leadless packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

### 13.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

### 13.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 11](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 8](#) and [9](#)

**Table 8. SnPb eutectic process (from J-STD-020C)**

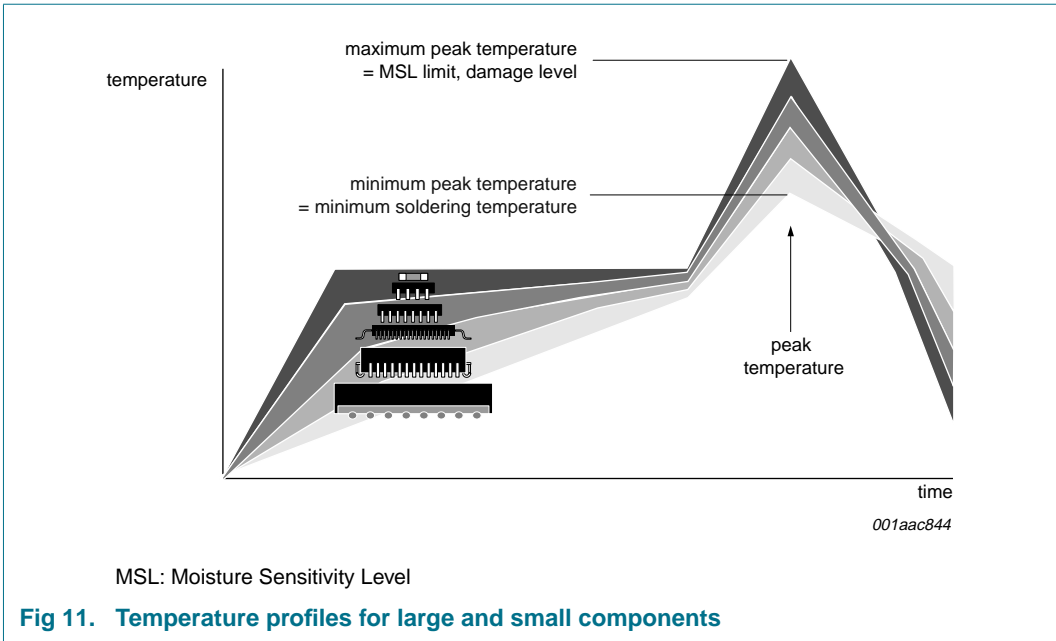
Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm <sup>3</sup> )	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

**Table 9. Lead-free process (from J-STD-020C)**

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm <sup>3</sup> )		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 11](#).



For further information on temperature profiles, refer to Application Note *AN10365* “Surface mount reflow soldering description”.

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
I/O	Input/Output
I <sup>2</sup> C-bus	Inter-Integrated Circuit bus
MM	Machine Model
RC	Resistor Capacitor network
SMBus	System Management Bus

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9518A_3	20081203	Product data sheet	-	PCA9518A_2
Modifications:	<ul style="list-style-type: none"><li>Section 6.1 "Enable": added new 3<sup>rd</sup> paragraph</li><li>Figure 5 "Typical application: multiple expandable 5-channel I<sup>2</sup>C-bus hubs": added 2<sup>nd</sup> paragraph below drawing.</li></ul>			
PCA9518A_2	20081001	Product data sheet	-	PCA9518A_1
PCA9518A_1	20070606	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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